

## **AMENDMENTS TO THE ABSTRACT**

**Please replace the abstract with the following substitute abstract.**

~~The present invention is intended for providing a~~A component mounting apparatus and a component mounting method which improve an accuracy and a rate of placement of components on a circuit-formed member. A component ~~+~~sucked by a suction nozzle ~~5~~is recognized at a component recognizing position ~~+~~ $\theta$ , a deviation  $\Delta L$  of the component ~~+~~ from a normal suction status ~~+~~ $b$  is determined on the basis of component recognition information obtained from the recognition of the component, and a velocity of conveyance of the component ~~+~~ for a period of time following the recognition of the component and preceding the placement of the component is controlled on basis of a magnitude of the deviation. By the control, the accuracy and rate of placement of the components ~~+~~ on the circuit-formed member ~~2~~ can be improved.